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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Chang-Rong WU et al. Confirmation No: 9777  
Appl. No. : 10/810,804  
Filed : March 29, 2004  
Title : Method And Composite Hard Mask For Forming Deep  
Trenches In A Semiconductor Substrate

TC/A.U. : 2823  
Examiner : F.L. Toledo

Docket No.: : WUCH3037/REF  
Customer No: : 23364

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of March 9, 2006, in connection with the above-identified application. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.